

PATENT ASSIGNMENT COVER SHEET

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|---|---|
| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| MARK I. GARDNER | 03/16/2020 |
| H. JIM FULFORD | 04/18/2020 |
| JEFFREY SMITH | 03/16/2020 |
| LARS LIEBMANN | 03/16/2020 |
| DANIEL CHANEMOUGAME | 03/16/2020 |
| RECEIVING PARTY DATA | |
| Name: | TOKYO ELECTRON LIMITED |
| Street Address: | AKASAKA BIZ TOWER, 3-1 AKASAKA 5-CHOME, MINATO-KU |
| City: | TOKYO |
| State/Country: | JAPAN |
| Postal Code: | 107-6325 |
| PROPERTY NUMBERS Total: 1 | |
| Property Type | Number |
| Application Number: | 16854340 |
| CORRESPONDENCE DATA | |
| Fax Number: | (703)413-2220 |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> | |
| Phone: | (703) 413-3000 |
| Email: | mkorsen@oblon.com |
| Correspondent Name: | OBLON, ET AL. |
| Address Line 1: | 1940 DUKE STREET |
| Address Line 4: | ALEXANDRIA, VIRGINIA 22314 |
| ATTORNEY DOCKET NUMBER: | 527302US |
| NAME OF SUBMITTER: | MATTHEW KORSEN |
| SIGNATURE: | /Matthew Korsen/ |
| DATE SIGNED: | 04/21/2020 |
| This document serves as an Oath/Declaration (37 CFR 1.63). | |
| Total Attachments: 12 | |

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**DECLARATION (37 CFR 1.63) AND ASSIGNMENT FOR
NONPROVISIONAL UTILITY OR DESIGN PATENT APPLICATION**

Title of Invention: METHOD FOR FABRICATION OF HIGH DENSITY LOGIC AND MEMORY
FOR ADVANCED CIRCUIT ARCHITECTURE

As a below named inventor, I hereby declare that:

This declaration and assignment is directed to:

The attached application having a docket number and title identified above, or
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The above-identified application was made or authorized to be made by me.

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I am aware of the duty to disclose to the United States Patent and Trademark Office all
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both.

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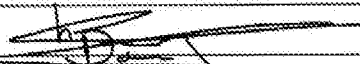
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(1) Legal name of Inventor: Mark I. GARDNER
Inventor's Signature: *Mark I. Gardner* Date: 3/16/2020
Residence City/State/Country: Cedar Creek, TX, United States
Mailing Address: c/o NanoFab 300 South, 255 Fuller Road, Suite 214, Albany, NY 12203
Citizenship: United States

(2) Legal name of Inventor: H. Jim FULFORD
Inventor's Signature: _____ Date: _____
Residence City/State/Country: Marianna, FL, United States
Mailing Address: c/o NanoFab 300 South, 255 Fuller Road, Suite 214, Albany, NY 12203
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(3) Legal name of Inventor: Jeffrey SMITH
Inventor's Signature: _____ Date: _____
Residence City/State/Country: Clifton Park, NY, United States
Mailing Address: c/o NanoFab 300 South, 255 Fuller Road, Suite 214, Albany, NY 12203
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Mailing Address: c/o NanoFab 300 South, 255 Fuller Road, Suite 214, Albany, NY 12203
Citizenship: United States

(5) Legal name of Inventor: Daniel CHANEMOUGAME
Inventor's Signature:  _____ Date: 03/16/2020
Residence City/State/Country: Niskayuna, NY, United States
Mailing Address: c/o NanoFab 300 South, 255 Fuller Road, Suite 214, Albany, NY 12203
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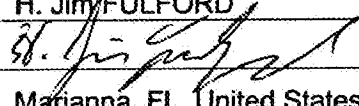
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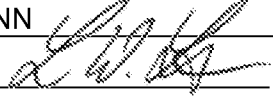
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